

國立交通大學

經營管理研究所

博士論文

No. 135



台灣IC設計產業的經營能力及智慧資本管理研究

Managerial Capabilities and Intellectual Capital
Management of IC Design Industry in Taiwan

研究生：陳達元

指導教授：楊 千 教授

中華民國一〇〇年一月

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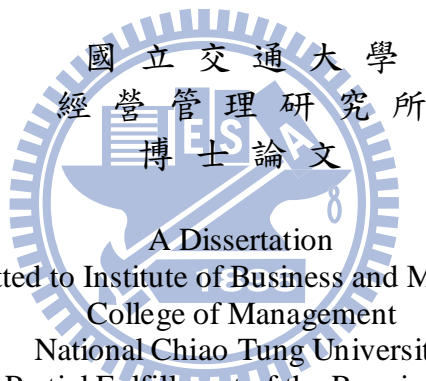
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Management of IC Design Industry in Taiwan

研究生：陳達元

Student：Ta-Yuan Chen

指導教授：楊 千

Advisor：Chyan Yang



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摘 要

過去二十年來，台灣IC設計產業經歷了快速的成長，已經成為了僅次於美國的全球第二大IC設計產業。IC設計產業具有變動快速、固定資產比率低以及知識密集度高等特性。然而，由於新技術不斷出現，IC設計產業也面臨了許多不確定性及衝擊。例如單晶片系統(SoC)技術的發展，就為台灣IC設計產業帶來了許多新的挑戰。此外，由於IC設計產業具有高度知識密集的特性，經營能力的優劣，以及對智慧資本的管理能力，就成了決定成敗的重要因素。

本論文回顧台灣IC設計產業的發展歷程，探討內在及外在的成功因素，進而探究單晶片系統技術對台灣IC設計產業可能造成的衝擊。另外本論文也針對經營能力及智慧資本的管理進行兩項實證性的研究。在經營能力的研究中，使用了三階段資料包絡法(3-stage Data Envelopment Analysis)對美國及台灣的主要IC設計公司進行相對競爭力的研究分析。在智慧資本的研究中，則以台灣IC設計公司為樣本，分析其經營效率，並提供相關的建議及管理意涵。

關鍵詞：IC設計、單晶片系統、模組化、標準、矽智財、經營能力、資料包絡法、智慧資本。

Managerial Capabilities and Intellectual Capital Management of IC Design Industry in Taiwan

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ABSTRACT

IC design industry in Taiwan has experienced dramatic growth over the past two decades. Taiwan IC design industry, behind the US, has become the second largest in the world. The characteristics of IC design industry are fast-changing, asset-light and knowledge-intensive. However, the emergence of new technologies may bring about uncertainty and impact. For example, the rise of System-on-a-Chip (SoC) design methodology has brought new challenges to Taiwan IC design industry. Since IC design industry is asset-light yet knowledge-intensive, the managerial capabilities and intellectual capital management are the critical issues for the industry.

The dissertation explores the external and internal factors that make Taiwan IC design industry successful. Besides, the characteristics of Taiwan IC design industry and the impact of SoC are studied. In addition, two empirical studies on managerial capabilities and intellectual capital management are conducted. The study of managerial capabilities employed 3-stage DEA to investigate the competitive landscape of dominate players in US and Taiwan IC design industry. The study of intellectual capital management compares the managerial efficiency of intellectual capital for IC design houses in Taiwan. The implications and recommendation resulting from the studies are provided.

Keywords: IC design; SoC; system on a chip; modularity; standards; SIP; managerial capability; DEA; intellectual capital

誌

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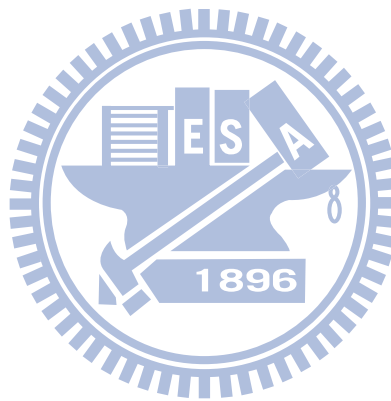
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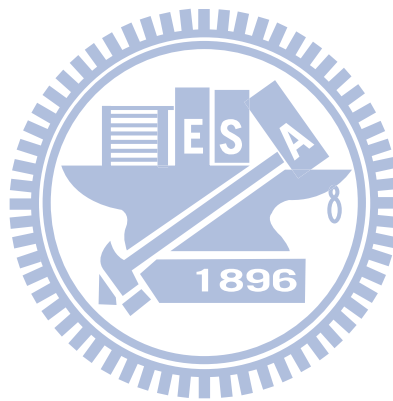
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Chapter 1. Introduction

1.1. Research Background

Taiwanese IC design industry has experienced dramatic growth over the past two decades. The compound annual growth rate (CAGR) of IC design industry in Taiwan is about 15% for the past 10 year (2000-2009). The rapid growth made Taiwanese IC design industry, behind the US, the second largest IC design industry in the world (Huang and Yang, 2003).

Compared to manufacturing, packaging and testing sectors in Taiwanese IC industry, the IC design sector is more suitable for Taiwan. Compared to other sectors in IC industry, the IC design sector generates higher gross margin and revenue per employee while consumes less capital expenditure at the same time. Furthermore, the high-quality yet relatively low-cost engineers have been the competitive edge for Taiwan. Developing IC design industry can fully utilize the valuable human resources thus strengthen Taiwan's competitive ability.

To analyze the prosperity of Taiwanese IC industry in the past two decades, Hung and Yang (2003) applied the national system of innovation (NSI) concept to explore the successful factors of Taiwanese IC design industry. Among the elements of an NSI, four factors are selected from the literature (Chen and Sewell, 1996; Mathews, 1997; Chang and Hsu, 1998). There are four major factors- "government policy", "human capital", "industry clusters", and "bridging institutions"- contributed to the success of Taiwanese IC design industry. To achieve the goal of "Green Silicon Island", Taiwan government used lots of policies - including tax benefits, low-interest loans, Industry-University Cooperation Program, and sponsoring R&D institution focusing on applied technology - to attract investment in IC industry. Besides, the high-quality human capital in Taiwan is the most valuable asset for high-tech development. Higher salaries and stock rewards in Taiwan IC industry help recruit skillful and dedicated engineers to boost the

industrial growth. Furthermore, the Shin-Chu Science-Based Industrial Park, Taiwan's "Silicon Valley", has provided a superb infrastructure to attract the first-tier high-tech firms to start their business. After years of development, an IC industry cluster has formed. The network structure facilitates personnel, technological, and informational interactions within the cluster. Therefore, technological diffusion, cooperation, and mutual support are easy to take place between firms. Finally, the most famous bridging institution, Industrial Technology Research Institute (ITRI), have made a great contribution to the development and diffusion of technology for Taiwan's high-tech industries. ITRI is responsible for scanning new technology globally, absorbing them and transferring these new technology to Taiwanese firms for commercial development. For example, the Taiwan's computer industry benefited a lot from the successful interaction with ITRI. (Chang et al., 1999) Furthermore, ITRI integrates government, academic, industrial and foreign resources to make the most of industrial innovation (Hsu, 2005). Since many Taiwanese firms are small-to-median enterprises and lack of R&D capability. ITRI have become the source of innovation for Taiwan IC industry. All these factors interact with each other and create synergy to enhance the growth of Taiwanese IC design industry.

The characteristics of IC design industry are fast-changing, asset-light and knowledge-intensive. The emergence of new technologies may bring about uncertainty and impact. The rise of System-on-a-Chip (SoC) design methodology has brought new challenges to Taiwan IC design industry. Since IC design industry is asset-light yet knowledge-intensive, the managerial capabilities and intellectual capital management are the critical issues for the industry. All the important issues mentioned above are summarized and defined in detail in section 1.2.

1.2. Scope and Objectives

1.2.1. The “Temporary Champion Curse” of IC design industry in Taiwan

IC design industry has been an increasingly important sector in Taiwan. Under a modular industrial structure, IC design houses in Taiwan can build their competitive advantages on speed, quality, flexibility and cost. However, modular structure of the industry also imposes restriction on the firms’ long-term growth and profitability. The “temporary champion curse” phenomenon, describing the growth ceiling and short-term competitiveness of specialized firms in a modular production system, was observed in IC design industry in Taiwan. The research depicts the “temporary champion curse” phenomenon in IC design industry and attempts to explore the reasoning through the lens of theory. The main finding is that knowledge scope is critical for firms to maintain long-term competitiveness. A firm should not only focus on their present products but expand their knowledge scope in the long run.

1.2.2. Managerial Capabilities of IC Design Industry

The IC design houses in US and Taiwan comprise 90% of market share around the world. The IC design firms, belonging to the fabless sector of semiconductor industry, rely little on physical capital investment. Capability, the central concept suggested by resource-based view (RBV), is the key factor to succeed in IC design industry. To measure relative capability, firms should be compared across similar external conditions and evaluated with multiple performance indicators. This research employed three-stage DEA to isolate environmental influence and included 30 dominant players of IC design industry to evaluate their managerial capabilities. The results showed that IC design houses in US outperform their counterparts in Taiwan. It is a warning signal that many IC design houses in Taiwan are inefficient and less profitable. The

results of this research provide practical information for managers of IC design houses to understand their relatively competitive positions and thus to frame their future strategies by benchmarking their counterparts.

1.2.3. Intellectual Capital Management of IC Design Firms in Taiwan

Management of intellectual capital has been the source of competitive advantages in the new economy. The study employed data envelopment analysis (DEA) and principal component analysis (PCA) to analyzed 62 publicly listed IC design firms in Taiwan. The DEA models using different performance indices were analyzed and their relationships were further explored with PCA. The empirical results revealed that 30 out of 62 firms are efficient in market value added (MVA) or calculated intangible value (CIV) performance dimension. About a quarter of the IC design firms still have much room to improve their intellectual capital management. The purpose of the study aims to provide a benchmark tool for firms to understand their relative strength and weakness in intellectual capital management. The empirical results may help managers frame their future strategy more correctly and enrich the empirical research on intellectual capital management.

1.3. Organization of the Dissertation

The dissertation is organized as the following order. Chapter 2 explores the “temporary champion curse” phenomenon of IC design industry in Taiwan, describing the growth ceiling and short-term competitiveness of specialized firms in a modular production system. Two empirical studies on managerial capabilities and intellectual capital management were conducted. Chapter 3 employed 3-stage DEA to investigate the competitive landscape of dominate players in US and Taiwan IC design industry. Chapter 4 compares the managerial efficiency of intellectual capital

for Taiwan IC design houses. The implication and recommendation are provided at the end of each chapter.



Chapter 2. The “Temporary Champion Curse” of IC design industry

2.1. Research background

IC design industry, fabless sector of the semiconductor, has been increasingly important for the semiconductor industry. The revenue percentage of the IC design sector in semiconductor industry has increased from 15% in 2003 to 17% in 2005 and reach 22% in 2008 (IEK, 2005). Most of the dominant players of IC design industry are located in US and Taiwan. The IC design houses in Taiwan and US comprise 90% of market share in the world. Second only to US, Taiwanese IC design industry has been the second largest in the world (Hung and Yang, 2003). Generally speaking, US IC design firms own more advanced technology, invest more in R&D, and enjoy higher gross margins than their counterparts in Taiwan. On the contrary, Taiwanese IC design houses, adopting the strategy as quick followers, build their core competence on speed, quality, flexibility and cost (Chang and Tsai, 2002).

The whole IC industry in Taiwan builds on the structure of vertical disintegration and specialization. The level of modularity in the IC industry is quite high. Langlois (2003) noted that modularity gives rise to a set of market-supporting institutions, stable interface standards and design rules. Under stable interface standards and design rules, modularity enables firms to pursue focused strategies and outsource across the value chain. That is why Taiwan IC industry can bring all its competitive strengths (speed, quality, flexibility and cost) into full play.

Although modular production system brings about the benefits of speed, quality, flexibility and cost reduction, it also imposes restriction on specialized firms' long-term growth. The “temporary champion curse” phenomenon, describing the growth ceiling and short-term competitiveness of specialized firms in a modular production system, was observed in IC design industry of Taiwan. This research tries to depict the “temporary champion curse” phenomenon in

Taiwan IC design industry and explore the reasoning through the lens of theory.

2.2. Modularity

2.2.1. Modular system

A complex system consists of subsystems that interact and interdependent to some degree (Sanchez and Mahoney, 1996). Complex systems can be classified into categories of decoupled, loosely coupled and tightly coupled systems according to the level of impact on the evolution of other components. In tightly coupled systems, components cannot be separated at all. On the contrary, components can change independently without impact on the evolution of other components in decoupled systems. In loosely coupled systems, components can perform a specific function separately and integrate as a whole system according to defined rules. Modular system is a loosely coupled system coordinated by specifying standard operating procedures (Cyert and March, 1963). A modular system relies on design rules which define the relationships of modules or components (Baldwin and Clark, 1997).

2.2.2. Benefits of modular system

Modular system can lower transaction costs of the whole system and thus bring about the benefits of speed, cost reduction and customization. On one hand, components in the same system can be reusable and interchangeable in other products. On the other, coordination and monitoring costs can be kept at minimum level by limiting information flows between activities.

A modular system is flexible since product variations can be achieved by replacing different modular components with no need to redesign other components (Sanchez, 1995). The flexibility of modular system allows of 'mixing and matching' of modular components and thus extends the

range of product variations. A firm can combine existing or new modular components to create new products to customize market demand. The strategic flexibility of modular system can be an important source of competitive edge because a firm can respond more quickly to changing markets and technologies (Sanchez, 1995). At last, by standardizing component interfaces, modular system can coordinate geographically dispersed component developers and thus make global production network possible (Kogut and Kulatilaka, 1994). This helps enhance more new product variations and enlarge scale economics.

2.2.3. Technological changes and modularity

In the early stage of product development, interdependent architectures usually predominate due to design complexity. On one hand, modular architecture may force designers to compromise and move away from advanced technological frontier in order to fit entrenched industry standards (Ulrich, 1995). On the other, employing new technologies in product design, engineers may not know what to specify, can not accurately measure important attributes and do not understand how the variation in subsystems will impact overall system performance (Christensen et al., 2002). The managerial efforts are needed to monitor developing processes closely in order to reduce transaction costs (Williamson, 1975). Therefore, it would be better to adopt the interdependent architecture and keep the developing activities in-house at the early stage of innovation.

In the late stage of product development, industry standards emerge and thus modularity creates the benefits of speed, cost reduction and customization (Baldwin and Clark, 2000). When one firm's interface specifications were accepted by other competitors, these specifications take form as industry standards. Employing industry standards, designers and assemblers can mix and match the most effective components from the best suppliers (Christensen et al., 2002). At this stage, modular architecture brings about the benefits of scale economics, speed to market, and

flexibility for horizontally stratified firms. Gradually, the dominated integrated firms will gradually replaced by independent focused providers (Baldwin and Clark, 2000).

When firms try to upgrade their product level, product development shit back to early stage and integrating ability become critical again. To adapt the dynamic market demand, firms have to update and modify their product designs quickly to meet new market requirements. The capabilities of creating new designs by recombining existing knowledge to meet dynamic market demand are essential for firms to keep competitive. At this stage, individual firms in a modular may lack the capability of integration due to their narrow knowledge scope.

2.2.4. Knowledge scope and competitiveness

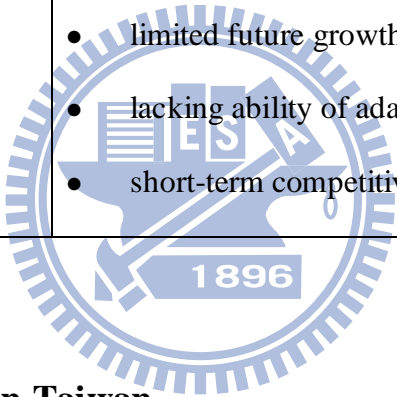
Broader knowledge may contribute to business competitiveness. The combination of technological specialization and application breadth is critical for continuous performance improvement (Iansiti, 1997). The more products employing a particular function to deliver it, the faster a firm will accumulate knowledge about barriers for functional performance and how to overcome them (Pil and Cohen, 2006). Besides, firms with multiple product lines have more diverse sets of organizational routines and broader knowledge scope. Wider knowledge scope enables firms to develop variant sets of routines to support broader search and increase routine recombination opportunities. When faced with an unexpected change, those firms with broader knowledge scope have greater chance to leverage and recombine existing knowledge to solve problems and create new opportunities. As a result, firms with broader knowledge scope gain competitive advantage in the long run. Studying the case of the building industry in the UK, Cacciatori and Jacobides (2005) propose that re-integration was necessary to build the capabilities to respond to market demand. Bercovitz and Mitchell (2007) also showed that multi-product firms will survive longer than single-product firms. An individual firm in a

modular value chain tends to specialize only in a narrow knowledge scope and thus may lack of enough re-integration capabilities to adapt changing market environment.

The advantages and disadvantages of specialized firms in a modular system are summarized in Table 2.1.

Table 2.1 Advantages and disadvantages of specialized firms in a modular system

Advantages	<ul style="list-style-type: none"> • small capital required • narrow knowledge scope required • competing on speed, quality, flexibility and cost
Disadvantages	<ul style="list-style-type: none"> • profit margin declining quickly • limited future growth potential • lacking ability of adapting varying market demand • short-term competitive advantages



2.3. IC design industry in Taiwan

2.3.1. Migration of IC design industry

Many firms today are outsourcing some of their value-added activities that do not belong to their competitive strengths to more cost-effective outside suppliers. To understand why chip design industry moved to Asia, Ernst (2005) interviewed with 60 companies and 15 research institutions in the US, Taiwan, Korea, China and Malaysia that are involved in electronic design. The author concluded that there are three factors (“pull”, “policy” and “push”) driving the chip design industry to move to Asia. “Pull” factor means: (1) the lower cost of employing a chip design engineer in Asia and (2) the rapidly growing Asian market. “Pull” factor gives global

integrated device manufacturers (IDMs) and system houses the incentives to set up their Asian design centers. Besides, to attract foreign investment, many Asian governments adopted the policy of providing low-cost yet well-established infrastructure and tax deduction to upgrade their domestic industries. “Police” factor played a catalytic role in providing necessary support to attract foreign investment and upgrade technological level. At last, “push” factor depicts that chip design has become a highly complex technology system, where different kinds of knowledge and skills need to be communicated and coordinated simultaneously. However, it’s too costly to keep a large group of diverse people at the same location. Vertical specialization in the global design network provides an efficient and flexible way to exchange the required knowledge for designing chip at a lower cost. This force push chip design industry to disperse globally and move to Asia. As a result, the migration of IC design industry brought foreign investment and advanced technologies thus helped Taiwan establish IC design industry.

Taiwanese IC design industry plays an important role in the global production network. Breznitz (2005) proposed Taiwanese IC design industry provides complementary assets to the Taiwanese OEMs and pureplay foundries and enhances the competitive advantage of the whole Taiwanese IT industry. The successful Taiwanese system houses and OEM companies, like BenQ and Quanta, created a large demand for chips based on second-generation technology. On the other hand, Taiwanese IC design firms provide system houses and OEM manufacturers with low-cost chips to lower their cost structure and thus maintain their competitive strengths. Besides, the existence of world’s second largest IC design industry supplied pureplay foundries with stable stream of orders to help them stay profitable as well as maintain and extend technological capacities. In short, the players of Taiwanese IT hardware industry – the system houses, pureplay foundries and IC design firms – strengthen each other’s competitive advantages and create synergy for the whole IT industry in Taiwan.

2.3.2. Characteristics of IC design industry in Taiwan

The successful companies in Taiwan IC industry exhibit some common characteristics. Fuller (2003) compared the success of pureplay foundries with failure of DRAM industry in Taiwan and concluded that Taiwan can become an innovator in the products with the following characteristics: “a high level of granularity in the production chain”, “high volume production”, “manufacturing-based outputs” and “no requirement for large amounts of patient capital”. Furthermore, Taiwanese companies did not try to challenge the technology leaders directly, but adopted the quick-follower strategy. Chang and Tsai (2002) analyzed the competitive strategy of Taiwan’s IC design industry and found the key competitiveness lies in “the speed to implement”, “the quality of the design output”, “flexibility in response to changes in specification and market demand”, and the “overall cost level”. The industry-wide standards allow product architecture to become modular. Modularity enables specialized firms to develop products that fit standardized interfaces without redesigning an entire product. That is why the firms in a modular value chain can beat competitors with speed, responsiveness and customization. The success of Taiwanese IC industry demonstrates all the aforementioned characteristics. Due to the modular industrial structure, Taiwanese IC design firms can bring their core competence (niche position) – speed, quality, flexibility and cost – into play.

2.3.3. The temporary champion curse

Although Taiwan IC design industry has achieved great success in the past two decades, there are still structural limits to firms’ long-term sustainable growth. The “temporary champion curse” phenomenon, describing the short-term competitiveness of IC design firms, was observed in IC design industry of Taiwan. Under a modular production system, a firm with small capital can select a focused niche product to entry market and enjoy high profit margin and high growth

rate in early stage. As time goes by, profit margins tend to decline and growth slow down quickly due to competition from market. If the company cannot product innovative products to meet varying market demand, the competitive advantage of the firm will not last long. Besides, there is also a growth ceiling for focused firms. There are few IC design houses in Taiwan can exceed the “one-billion” revenue barrier. To conclude, the “temporary champion curse” describes the short-term competitive edge and revenue limit experienced by most firms in IC design industry of Taiwan. Fig. 2-1 shows the revenue growth curve of top 20 IC design firms since 1999. For the past ten years, only one company, Media Tek, has grown beyond the one-billion barrier. Fig. 2-2 shows annual compound growth rate (CAGR) and average gross margins of top 20 IC design firms in Taiwan. As shown in Fig. 2-2, most of the firms’ margins are below 40%. There is only one company, Media Tek, enjoying high annual growth rate and profit margin compared to other peer companies.

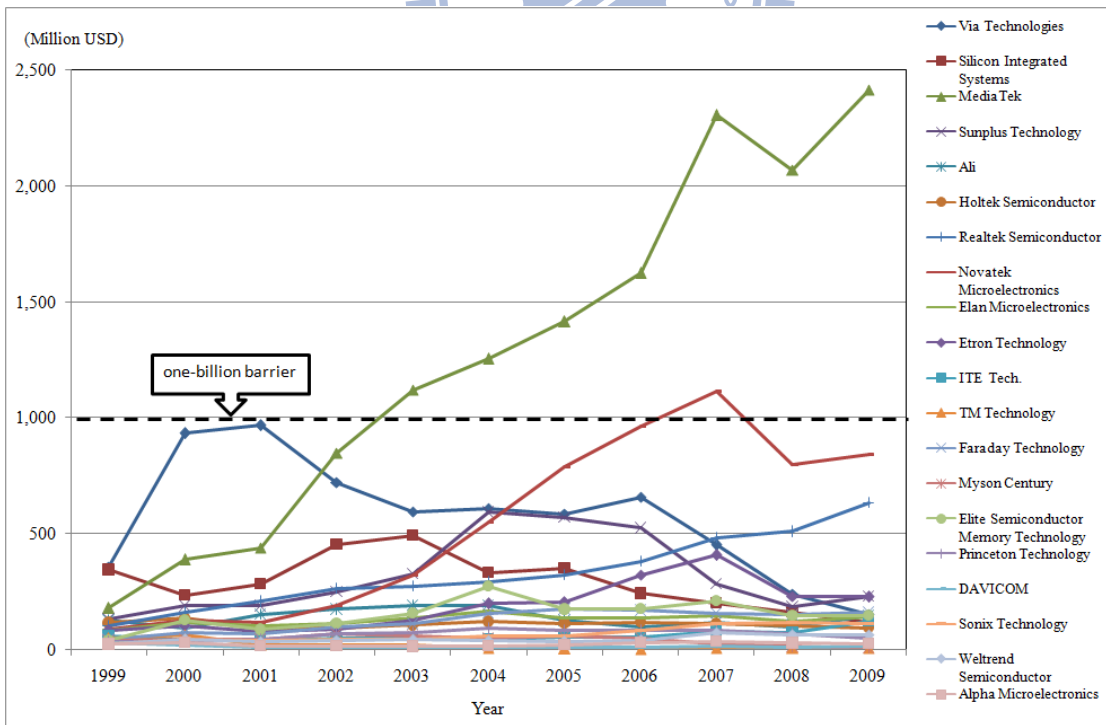


Fig. 2-1 Revenue growth of top 20 IC design houses since 1999
Source: Taiwan Economic Journal (TEJ)

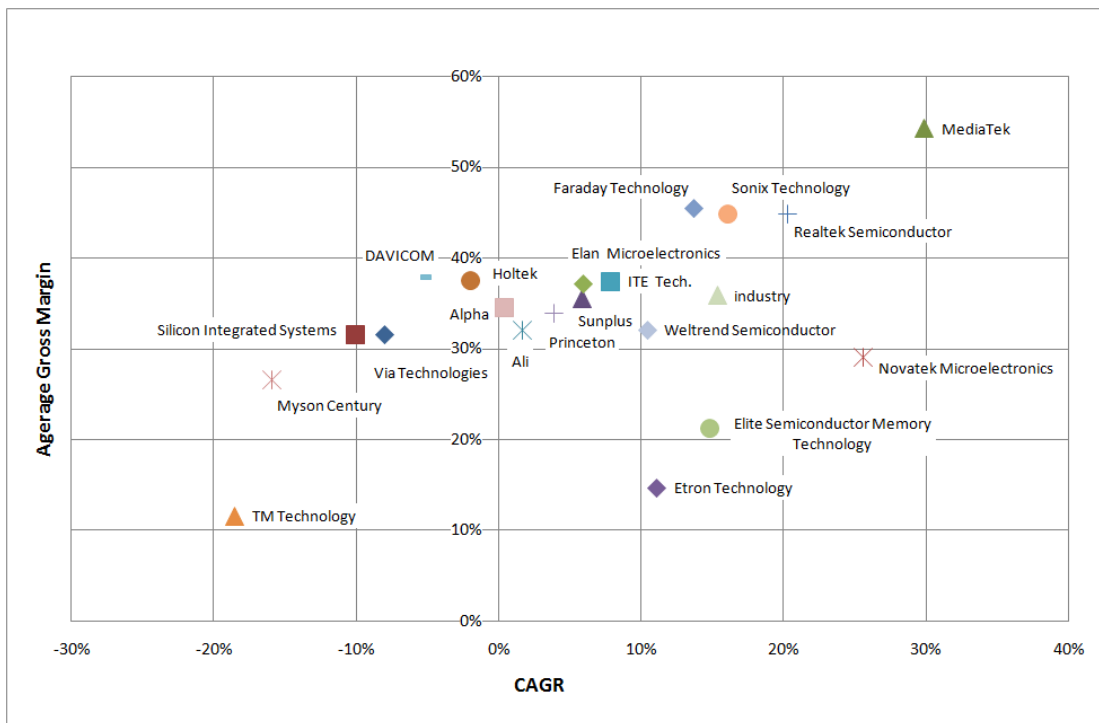


Fig. 2-2 CAGR and average gross margin of top 20 IC design houses between 1999 and 2009
Source: Taiwan Economic Journal (TEJ)

2.4. Market and technological change in IC design industry

The performance requirements for electronic products have been increasingly demanding for the recent years. Multiple 3Cs (Computing, Communication and Consumer) functions are required to be integrated in a single electronic device. To be more competitive in the market, electronic products strive to be lighter, thinner, shorter, smaller, as well as less power-consuming at the same time. Besides, time pressure to launch a new product is another critical issue. Product life cycles of electronic products have been rapidly shrinking to a few months, while designing a new chip still needs months or years. To solve all the problems mentioned above, the new design methodology, “System-on-a-Chip” (SoC), emerged as an effective solution. According to

Dataquest's survey, the market share of SoC design grew rapidly from 18.6% in 2004 to 22.7% in 2008.

The widening productivity gap between manufacturing and design has been another main driving force to apply the SoC design methodology. Following Moore's law, the complexity and density of ICs have increased rapidly. While the manufacturing productivity of semiconductor has seen a 58% compounded annual growth rate, improvements in the productivity of IC designer failed to keep up (only a 21% compound annual growth rate) (SIA, 1999). To bridge the productivity gap, IC design engineers need to employ new reusable design methodology to reduce recurring cost and shorten product life cycles. The physical components assembled on a PCB will be gradually replaced by the virtual components (SIPs) integrated on a software platform. Applying the "platform design" concept, the specific functions of a system are designed as modules (silicon intellectual property, SIPs) to replace IC components then integrated on a single chip. The SoC design methodology can systematically reuse as many design steps as possible thus reduce development time and related costs.

In an industry with high modularity, all the work in a value chain can be clearly defined and divided. Baldwin and Clark (2000) stated that "modularity is a particular design structure, in which parameters and tasks are interdependent within units (modules) and independent across them." Therefore, a firm without system integration knowledge can focus on its own expertise and provide complementary service to other companies under a modular industry structure. As a result, the whole value chain can benefit from efficiency and lower cost. The same modular concept is expected to be applied in the SoC design methodology. The virtual electronic components (SIPs) will be integrated on a design platform just as physical electronic components are fabricated on a printed circuit board (PCB). However, platform design does not reduce the need for system integration knowledge. In the PCB paradigm, individual firm can manufacture

electronic components according to industry-wide standards. System integration knowledge is not a requirement for the specialized component providers. Therefore, coordination across firm boundary can keep at a minimum level. Shifting to SoC paradigm, the platform design only provides “a common base for the manifestation of differentiated systems knowledge” (Martin, 2003). Christensen (2004) stated that when a product or service is not good enough, firms with integrating ability are best suited to coordinate the complexity of developing new product. To improve product, firms often need to recombine existing technologies in new ways and thus creating new patterns of interaction and new problems. System integration capability is critical to overcome the increasing technical difficulty originating from technological complexity and fast technological changes. As shown in Fig. 2-3, IC design technique is moving from a modular architecture to an interdependent architecture in SoC era.

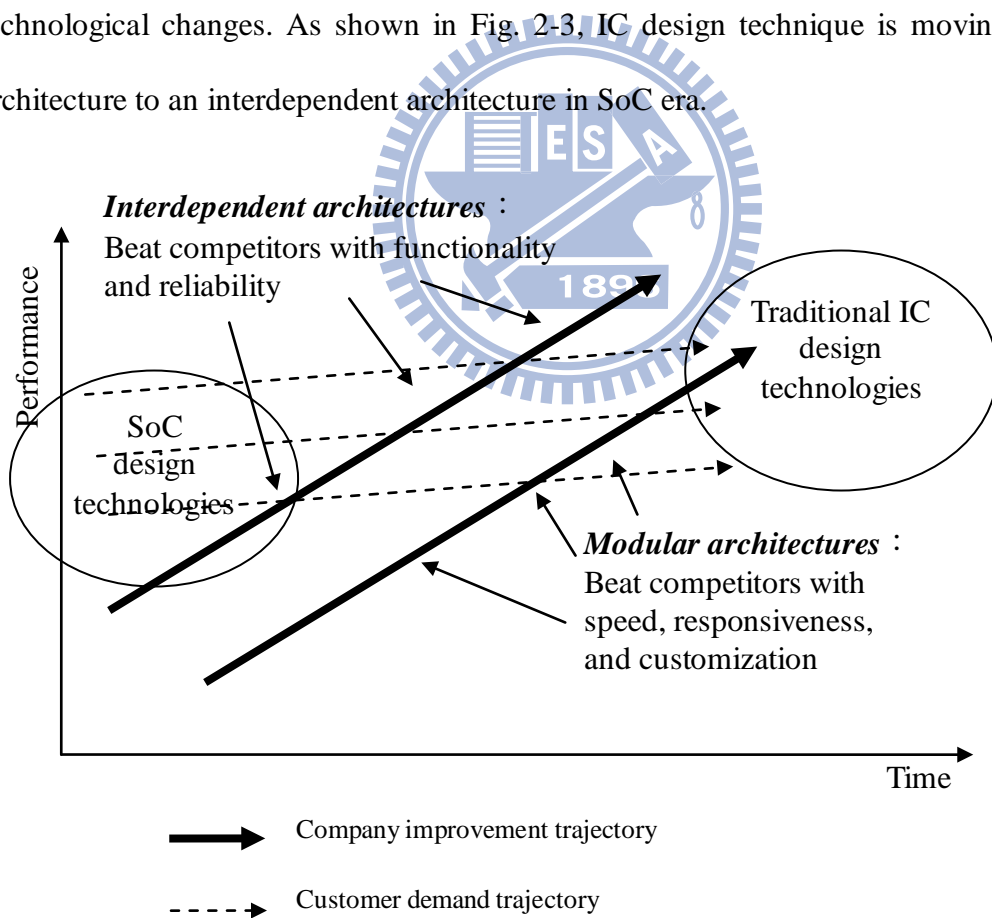


Fig. 2-3 Architecture shift in SoC era

2.5. The enduring champion in Taiwan IC design industry

Although many IC design houses in Taiwan suffer the temporary champion curse, there is one exception, MediaTek, for the temporary champion curse in Taiwan. As shown in Fig. 2-1 and Fig. 2-2, MediaTek has enjoyed high profit margin and broken the one-billion growth ceiling for the past ten years. MediaTek Inc., founded in 1997, is headquartered in Taiwan and has sales and research subsidiaries in Mainland China, Singapore, India, U.S., Japan, Korea, Ireland, Denmark and England. MediaTek is a leading fabless semiconductor company for wireless communication and digital media solutions. Since its establishment, the compounded annual sales growth rate of the Company has reached 30% and it enjoyed more than 40% gross margin every year. In terms of revenue perspective, MediaTek is also one of the world's top 10 fabless semiconductor companies.

Unlike many of its counterparts in the industry, MediaTek continually expand its product range and knowledge scope. MediaTek was originally a CD/DVD chipsets manufacturer when established in 1997. To enlarge its knowledge scope, MediaTek participated aggressively in global mergers and acquisitions. The company acquired NuCORE Technology Inc., a US digital camera chipset design company. It also purchased the Othello® radio and SoftFone® baseband chipset product lines as well as certain cellular handset baseband support operations of Analog Devices, Inc. These acquisitions allowed MediaTek to break through critical technologies and expand its knowledge scope to adapt varying market demand. As shown in Table 2.2, MediaTek has transformed itself from a CD/DVD chipsets provider to an integrator of multiple advanced technologies like mobile phone, LCD TV, GPS and blue-ray disc for the past ten years. The ability of integrating multiple technologies is especially important in SoC era. That is why MediaTek can sustain its long-term competitive advantage and keep its growing dynamics.

Table 2.2 Technical milestones of MediaTek

Technical Milestones	
1997	MediaTek founded
1998	Launched CD-ROM Chipsets
1999	Launched DVD-ROM Chipsets
2000	Launched CD-R/RW Chipsets
2001	Launched Highly Integrated DVD-Player Chipsets
2002	Launched COMBI Chipsets
2003	Launched DVD-Dual Chipsets
2004	Launched GSM Mobile Phone Chipsets
	Launched GSM/GPRS Cell Phone Chipsets
2005	Launched HD LCD TV Controller Chips
	Launched ATSC / DVB-T HD LCD TV Chipsets
2006	Launched GSM/GPRS/EDGE Multimedia Application Process
2007	Launched GPS Receiver Single Chip
	Launched First Generation Blue-Ray Chips
2008	Launched Full HD ATSC iDTV SOC
2009	Launched High Sensitivity GPS SOC

Source: website of MediaTek (<http://www.mediatek.com/en/corporate/awards.php>)

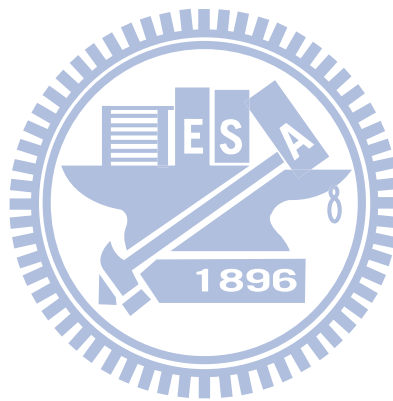
2.6. Conclusion and implication

This research attempts to describe the “temporary champion curse” phenomenon in Taiwan IC design industry and explore the reasoning through the lens of theory. The “temporary

champion curse” phenomenon indicates the growth ceiling and short-term competitiveness of specialized firms in a modular production system. Modular production system makes possible for firms with small capital and narrow knowledge scope to enter market. However, the success achieved in early stage may not be sustainable in the long run. The abilities of mixing existing routines to match future change are critical for firms to accommodate varying environment. The knowledge specialized firms accumulated may be too narrow to adapt to future technological or market changes. That is why “temporary champion curse” phenomenon” was observed often in modular production system.

The past success of Taiwan IC design firms relied on the structure of vertical specialized network in IC industry. The competitive strengths of Taiwanese IC design firms include speed, quality, flexibility and low costs. All these strengths originate from the modular industry structure in which industry-wide standards are ready and stable. However, at the advent of SoC era, the “plug-and-play compatible” industry-wide standards are still not ready. It is hard to duplicate the past success in the PCB paradigm when design methodology is shifting to SoC. Furthermore, in an industry with high modularity, individual firm can just focus on its expertise without the knowledge of system integration. That is just the business model adopted by most of the IC design firms in Taiwan. With the help of industry-wide standards, the production processes can be coordinated automatically across firm boundary. In the SoC paradigm, all the physical components are replaced by SIPs which will be integrated on a single chip. The knowledge of system integration has been a requirement for SoC design. For Taiwanese IC design firms, lacking integrating ability will be an obstacle to overcome in the future. The successful story of Media Tek suggests focused firms should enlarge their knowledge scope to improve their abilities of adapting changing environment.

The “temporary champion curse” phenomenon observed in IC design industry of Taiwan generates some implications for specialized firms in a modular production system. Although specialized firms can enter market by selecting a niche product, in early stage, these firms may enjoy high profit margin and growth rate. However, the knowledge scope these firms accumulate is quite narrow. Therefore, the abilities of mixing existing knowledge to match future market demand are limited. In the long run, the future growth is restricted and profit margin will be declining. Therefore, it is important for the specialized firms in a modular production system to plan their future evolving path. They should not only focus their attention on present operation but also on expanding their future knowledge scope.



Chapter 3. Empirical Study on Managerial Capabilities of IC Design Houses

3.1. Research background

The IC design industry, fabless sector of the semiconductor, has been increasingly important for the semiconductor industry. The revenue percentage of the IC design sector in semiconductor industry has increased from 15% in 2003 to 17% in 2005 and reached 22% in 2008. (ITRI IEK, 2005). Most of the dominant players of IC design industry are located in US and Taiwan. The IC design houses in Taiwan and US comprise 90% of market share around the world. Second only to US, Taiwanese IC design industry has been the second largest in the world (Huang and Yang, 2003). Generally speaking, US IC design firms own more advanced technology, invest more in R&D, and enjoy higher gross margins than their counterparts in Taiwan. On the contrary, Taiwanese IC design houses, adopting the strategy as quick followers, build their core competence on speed, quality, flexibility and cost (Chang and Tsai, 2002). The different characteristics between Taiwan and US are listed in Table 3.1.

Table 3.1 Characteristics of IC design houses in US and Taiwan

Characteristics	US	Taiwan
R&D cost/Revenue (%)	19.30%	9.60%
Gross Margin (%)	49.30%	37.40%
Firm size	large	Small to median
Employing 90 nano-meter technology (%) in 2003	20%	0%
Employing 90 nano-meter technology (%) in 2005	50%	<10%
Products	High-speed network High-level graphic cards Wireless communication FPGA ^b	MCU ^a Memory chips DVD chips LCD driver chips

Annual costs of employing a chip design engineer (in USD)	300,000	< 60,000
Competitive advantages	Technology leader	Speed, quality, flexibility and cost

^aMCU: Micro Control Unit; ^bFPGA: Field-Programmable Gate Array
Source: ITRI IEK-ITIS project (2003-2005)

In spite of the increasing importance of IC design industry, the competitive landscape in the industry has seldom been explored. IC design houses, belonging to the fabless sector of the semiconductor industry, rely little on physical capital investment. Managerial capability is the key factor to succeed in IC design industry which relies little on physical capital investment. As suggested by resource-based view (Teece, 1980; Wernerfelt, 1984; Barney, 1991; Perteraf, 1993) capability is often embedded with the whole organization and hard to imitate or buy. Besides, capability is hard to observe or measure. In strategic literature, data envelopment analysis (DEA) or stochastic frontier analysis (SFA) have been applied to measure capability (Majumdar 1998; Dutta et al. 2005). When conducting research of comparing performance between countries, the 3-stage DEA approach is valuable for its ability of accounting for environmental factors (Avkiran and rowlands, 2008). Following previous research, this study employed three-stage DEA to inspect the capabilities of IC design houses.

This research tries to address the following issues: (1) to investigate whether the environmental differences between US and Taiwan have any impacts on efficiency ; (2) to evaluate the relative performance of dominant IC design houses after purging the influence of environmental factors and luck; (3) to reveal the relative competitive positions of IC design industry. The findings could be helpful for practitioners in IC design industry to understand their competitive positions and thus to frame their future strategies by benchmarking their

counterparts.

3.2. Literature Review

3.2.1. Capability

The central question in strategic management is to answer why some companies outperform others. The resource-based view (RBV), which tries to answer the question by inspecting the differences between companies, has been increasingly popular in strategic management field. The RBV logic links superior firm performance to the resources and capabilities owned by firms (Teece, 1980; Wernerfelt, 1984; Barney, 1991; Perteraf, 1993). Resources are stocks of available factors - property, plant and equipment, human capital, etc. - that are owned or controlled by a firm. Capabilities, in contrast, refer to a firm's capability to deploy resources (Amit and Schoemaker, 1993). While resources are observable assets that can be individually valued and traded, capabilities, on the other hand, are embedded with the whole organization and thus can be transferred only through sale of a firm (Makadok, 2001). Since these abilities are hard to observe, as RBV theory suggests, they would also be hard to imitate or buy. In spite of its popularity in strategic management field, RBV has suffered criticism for its conceptualization and measurement. Therefore, a different approach for measurement is required to address the issues mentioned above.

RVB has been criticized for its conceptualization and measurement. On one hand, some researchers have argued that the conceptualization of RBV is a tautology (Priem and Butler 2001). Porter (1994) and Williamson (1999) pointed out that most empirical studies identify critical resources and capabilities by comparing successful firms with unsuccessful ones, and then test whether these identified resources and capabilities are critical. Needless to say, the answer is

always a yes. That is why RBV is criticized as tautology.

On the other hand, many prior empirical studies of RBV are based on the doubtful financial ratios. Accounting ratios, such as return on total asset (ROA), return on investment (ROI) and return on sales (ROS) have been widely employed to measure firms' performance. However, relying on accounting ratios may result in some disadvantages. First, accounting ratios fail to reflect the multi-dimensional characteristic (multiple inputs and outputs) of the production process. In addition, accounting ratios may provide misleading information due to earnings management (Jones, 1991; Dechow et al., 1995; Shivakumar, 2000).

To address the issues of conceptualization and measurement in RBV, a different approach to measure capabilities is in need. First, the conceptualization and measurement of capabilities should be independent of their rent generation ability. Second, the measure of capabilities should be multi-dimensional and free from distortion. As Peteraf and Barney (2003) proposed, RBV is “an efficiency-based explanation of performance differences.” The quantitative techniques such as data envelopment analysis (DEA) or stochastic frontier analysis (SFA) may satisfy the requirements mentioned above.

3.2.2. Measurement of capabilities

The DEA and SFA techniques have been applied in much strategy literature (Majumdar, 1998; Majumdar and Venkararaman, 1998; Majumdar and Marcus, 2001; Dutta et al., 2005, Delmas and Tokat, 2005). For example, Majumdar (1998) used DEA to measure the capabilities of utilizing resources, using the U.S. telecommunications industry as a context. Dutta et al. (2005) applied SFA to demonstrate the heterogeneity of R&D capability across firms in U.S. semiconductor industry. Delmas and Tokat (2005) employed DEA efficiency scores as a dependent variable to tests the effects of deregulation and governance s structures in U.S. electric

utility sector. Since DEA compared the firms' capabilities in a relative sense, Dutta et al. (2005) suggested researchers have to ensure that capabilities are compared across similar external conditions. However, the traditional DEA model employed in many empirical studies is deterministic. That is, the DEA efficiency scores may comprise the effects of managerial capabilities, environmental influence and luck (Fried et al., 2002). It is not clear that the superior performance of a firm in DEA analysis is due to managerial capabilities or just due to favourable environment and luck.

To address this issue, this research employed the three-stage DEA analysis (Fried et al., 2002) to isolate the effects of environment and luck from managerial capabilities. The purpose of this study is to find out the "pure" managerial capabilities of IC design firms, using the IC design houses in U.S. and Taiwan as a context.

3.3. Research methodology

3.3.1. The Three-Stage DEA Model

Producer performance may be influenced by three different factors. The first is the ability of management to coordinate the related production activities. The second is the effect of environment under which production activities are performed. The third is the influence of luck or omitted variables which will be reflected in a random error term in a regression-based evaluation of performance (Fried et al., 2002).

To isolate the environmental effects and statistical noise from managerial efficiency, Fried et al. (2002) proposed the three-stage DEA model. In the first stage, conventional DEA analysis is conducted to obtain an initial evaluation of producer performance. However, the efficiency scores generated from the first stage still compose of all the effects including managerial efficiency,

environmental influence and statistical noise. Therefore, in the second stage, SFA technique will be employed to separate environmental effect and statistical noise from managerial efficiency. In the third stage, the original efficiency scores generated from the first stage will be adjusted to eliminate environmental influence and statistical noise. The environmental effects and statistical errors estimated in the second stage will be adjusted and a more “pure” managerial efficiency score will be produced. More details are provided in the following sections.

3.3.2. Stage 1: The Initial DEA Producer Performance Evaluation

The conventional DEA analysis is employed to conduct the initial performance evaluation. This study adopts an input-oriented approach and the assumption of variable return to scale (VRS) (Banker et al., 1984) to formulate the linear programming problem :

$$\begin{aligned}
 & \min_{\theta, \lambda} \theta & (1) \\
 \text{Subject to} & \quad \theta x^0 \geq X\lambda \\
 & \quad Y\lambda \geq y^0 \\
 & \quad \lambda \geq 0 \\
 & \quad e^T \lambda = 1
 \end{aligned}$$

where $X \geq 0$ denotes $N \times 1$ vector of inputs, $Y \geq 0$ denotes $M \times 1$ vector of outputs, $X = [x_1, \dots, x_I]$ is an $N \times I$ matrix of input vectors, $Y = [y_1, \dots, y_I]$ is an $M \times I$ matrix of output vectors, $\lambda = [\lambda_1, \dots, \lambda_I]$ is an $I \times 1$ vector of intensity variables, $e = [1, \dots, 1]$, and there are I producers in the comparison set. The optimal values of θ , solved by the above linear program equation, will fall between 0 and 1.

3.3.3. Stage 2: Using SFA to Decompose Stage 1 Slacks

The objective of the stage 2 is to decompose the slacks of the first stage into environmental influences, managerial inefficiencies and statistical noise. By applying stochastic frontier analysis (SFA), the slacks of inputs ($s_{ni} = x_{ni} - X_n \lambda \geq 0$) are regressed against observable environmental variables (z_i). The SFA regressions estimating cost frontier can be specified as:

$$s_{ni} = f^n(z_i, \beta_n) + v_{ni} + \mu_{ni}, \quad n = 1, \dots, N, \quad i = 1, \dots, I \quad (2)$$

The $f^n(z_i, \beta_n)$ terms are the deterministic feasible slack frontiers with estimated parameter vector β_n and composed error structure ($v_{ni} + \mu_{ni}$). The $v_{ni} \sim N(0, \sigma_{vn}^2)$ error reflects statistical noise, while the μ_{ni} error reflects managerial inefficiency. After all the effects are decomposed in equation (2), producers' adjusted inputs can be constructed by the following equation:

$$x_{ni}^A = x_{ni} + \left[\max_{\gamma_i} \left\{ z_i \hat{\beta}_n \right\} - z_i \hat{\beta}_n \right] + \left[\max_{\delta_i} \left\{ v_i \right\} - v_i \right] \quad n = 1, \dots, N, \quad i = 1, \dots, I \quad (3)$$

x_{ni}^A are adjusted input quantities, while x_{ni} are observed ones. The first adjustment in equation (3) eliminates the influence of environmental factors. And the second adjustment adjusts the influence due to luck. These adjustments will be different both across producers and across inputs. Finally gamma value $\gamma^n = \sigma_{un}^2 / (\sigma_{vn}^2 + \sigma_{un}^2)$ denotes the relative level of impacts originating from managerial inefficiency. When the value of gamma is close to 1, the influence of managerial inefficiency will dominates that of statistical noise.

3.3.4. Stage 3: Adjusted DEA

Stage 3 repeats stage 1 DEA analysis by employing adjusted input data. Since the effects of the operating environment and statistical noise have been removed, the efficiency scores

generated in stage 3 reflects only “pure” managerial efficiency.

3.5. Data

3.5.1. Data collection

IC design houses, belonging to the fabless sector of the semiconductor industry, rely little on physical capital investment. Managerial capability is the key factor to succeed in the industry. Thus, the IC design industry is an ideal sample for research on evaluating capability. The data employed in this study was collected from two electronic databases: Compustat and Taiwan Economic Journal (TEJ). Since top players dominate IC design industry, the top 15 IC design firms in US and top 15 ones in Taiwan were selected as samples. The aggregated revenues of these 30 companies accounted for about 70% of total IC design industry revenues in 2008, therefore the selected samples may well represent the whole industry. Panel data were collected during 2003-2008 and the total sample size is 180. To eliminate the inflation effects, all data were deflated with wholesale price index deflator to convert monetary values into constant 2006 US dollars.

3.5.2. Input and output variables

Following previous research in high-tech context, capital (CA) (Shao and Lin, 2002), R&D expense (RD) (Verma and Sinha, 2002) and number of employees (EMP) (Shao and Lin, 2002; Wu et al, 2006) were employed as inputs variables. As for outputs, this study adopted both accounting-based and market-based measures of performance. Accounting-based measures, including total revenue (TR) (Wu et al., 2006) and gross profit (GP), evaluate the past performance reported on financial statements. Since the IC design industry is highly competitive, the profit margins of IC design firms also decline rapidly. As indicated by president of MediaTek,

the largest IC design company in Taiwan, gross margin is the key performance index to keep competitive in IC design industry (Tsai, 2002). Adopting both revenue and gross profit may reflect the key performance dimension of IC design industry. Market-based measures such as market-to-book ratio (Crossland and Hambrick, 2007), on the other hand, reflect the willingness of stock market to pay premiums in excess of book value for certain firms. In general, high market-to-book ratio reflects expectation of stock market about a firm's future growth potential. For IC design industry, this premium part reflects the intellectual capital or knowledge capital created by IC design houses which is not reported on traditional financial statements. Besides, the premium value is especially important for high-tech firms to ensure sufficient capital inflow to fuel their future growth. In this research, market value (MV) is adopted as an output measure. Table 3.2 presents the descriptive statistics of all input and output variables.

Table 3.2 Descriptive statistics of IC design houses, 2003-2008 (sample size = 180)

Variables	Mean	Std. Deviation	Minimum	Maximum
Outputs:				
TR ^a	976,839.12	1,500,002.35	36,868.76	10,690,609.15
GP ^a	518,952.49	1,021,813.37	5,866.15	7,852,466.23
MV ^a	4,373,556.68	11,663,536.75	9,687.36	74,927,063.65
Inputs:				
CA ^a	1,093,651.86	2,360,117.60	10,289.81	16,290,984.22
RD ^a	182,841.64	325,242.66	1,569.05	2,188,590.87
EMP ^b	1,573.49	2,193.29	85	15,400

^aUSD in thousand; ^b number of employees

3.5.3. Environmental Variables

Environmental variables are defined as the external factors that firms cannot change easily during the time frame of analysis. Four types of environmental variable are specified: country, products, size, and age. As shown in Table 3.1, the different characteristics between US and

Taiwan are operating environment, product category, and firm size. Since one objective of this research is to investigate whether these environmental differences cause any impact on operating efficiency, country (Taiwan, US) is the dummy variable employed to denote the operating environment of firms. Besides, there are three major product categories in IC design industry: computer-related, communication-related and consumer-related products. Product dummies (computer, communication, consumers and others) represent different product categories to which firms belong. In addition, size is an important control variable to be included, since equally efficient small and large homes will have different levels of absolute slack (Fried et al., 2002). Capital is used as a measure of size in this research. At last, the influence of age on efficiency is explored. On one hand older companies may be more efficient due to their accumulated experience (Barnett et al., 1994), and on the other aged companies tend to be less flexible, less innovative and thus less efficient (Makhok and Osegowitsch, 2000). Therefore, this study adopts age variable to investigate whether the influence of age exists. All the variables characterizing environmental differences are listed in Table 3.3.

Table 3.3 Profile of IC design houses in US and Taiwan

No	Company	Country	Product Category	Start year
1	ADAPTEC	US	PC	1981
2	ALTERA	US	Others	1983
3	BROADCOM	US	Communication	1991
4	CIRRUS LOGIC	US	Consumer	1984
5	MARVELL TECHNOLOGY GROUP	US	Communication	1995
6	NVIDIA	US	PC	1993
7	OMNIVISION TECHNOLOGIES	US	Consumer	1995
8	PMC-SIERRA	US	Communication	1983
9	QLOGIC	US	Communication	1992
10	QUALCOMM	US	Communication	1985
11	SANDISK	US	Consumer	1995

12	SEMTECH	US	Others	1960
13	SILICON LABORATORIES	US	Communication	1996
14	SILICON STORAGE TECHNOLOGY	US	Others	1989
15	XILINX	US	Others	1984
16	MEDIATEK	Taiwan	Consumer	1997
17	NOVATEK MICROELECTRONICS	Taiwan	Consumer	1997
18	REALTEK SEMICONDUCTOR	Taiwan	Communication	1987
19	COASIA MICROELECTRONICS	Taiwan	Others	1997
20	VIA TECHNOLOGIES	Taiwan	PC	1992
21	ETRON TECHNOLOGY	Taiwan	Consumer	1991
22	RICHTEK TECHNOLOGY	Taiwan	PC	1998
23	SITRONIX TECHNOLOGY	Taiwan	Consumer	1992
24	SUNPLUS TECHNOLOGY	Taiwan	Consumer	1990
25	SILICON INTEGRATED SYSTEMS	Taiwan	PC	1987
26	FARADAY TECHNOLOGY	Taiwan	Others	1993
27	ELITE SEMICONDUCTOR MEMORY	Taiwan	Consumer	1998
28	PIXART IMAGING	Taiwan	Consumer	1998
29	ELAN MICROELECTONICS	Taiwan	Consumer	1994
30	SONIX TECHNOLOGY	Taiwan	Consumer	1996

3.6. Empirical results

In Stage1 DEA, initial efficiency scores were calculated year by year for Stage 2 SFA analysis. In Stage2 analysis, the efficiency scores calculated from 2003-2008 data were pooled to compute the three input slacks: capital slack, R&D expense slack and employees slack. Then each input slack is used as a dependent variable to run SFA analysis by employing environmental variables as independent variables. The results are listed in Table 3.4.

Table 3.4 SFA results (sample size = 180)

Independent Variable	Dependent Variable		
	Capital Slack	R&D Expense Slack	Employees Slack
Constant	-2.428 (2.193)	-2.170 (2.078)	-1.219 (1.257)
US	0.142 (1.598)	0.113 (1.445)	-0.122 (0.864)
Communication	1.337 (2.376)	1.574 (2.041)	0.580 (1.269)
Consumers	-0.779 (1.797)	-0.554 (1.620)	-0.347 (1.010)
Others	-0.657 (2.202)	-0.351 (1.906)	-0.213 (1.206)
Size	-4.65E-07 [†] (2.46E-07)	-4.17E-07 [†] (2.21E-07)	-1.98E-07 (1.32E-07)
Age	0.258 ^{**} (0.081)	0.202 ^{**} (0.069)	0.124 ^{**} (0.037)
sigma-squared	32.563 ^{**} (8.957)	24.750 ^{**} (6.654)	9.132 ^{**} (2.856)
gamma	0.573 ^{**} (0.123)	0.551 ^{**} (0.124)	0.606 ^{**} (0.127)
mu	6.461 ^{**} (2.395)	6.289 ^{**} (2.085)	3.332 [*] (1.387)
eta	-0.042 (0.025)	-0.057 [*] (0.027)	-0.050 [*] (0.025)
log likelihood function	-519.283	-498.087	-398.344
LR test of the one-sided error	54.056	50.595	58.615

[†]Significant at the 10% level ^{*}Significant at the 5% level ^{**}Significant at the 1% level

As shown in Table 3.4, for all three output slacks, the coefficients of country are not significant. This implies the operating environment of Taiwan is not inferior to that of US. For different product categories, the coefficients are also insignificant. That is, product categories to which a firm's products belong have no impact on inefficiency. The size coefficients of capital and R&D slack about are negative and significant at 10% significant level. The result suggests

larger firms tend to more efficient in usage of capital and R&D expense. Finally, age has positive relationship with all input slacks. This implies older firms tend to be more inefficient in managing all inputs.

The estimated values of gamma for all three inputs are 0.573 for capital slack, 0.551 for R&D expense slack and 0.606 for Employee slack. The result suggests that statistical noise explains about 40-45% variation of all three input slacks. In other words, more than half of slacks come from managerial inefficiency. There is still much room for individual managers to improve.

In Stage3 analysis, all input slacks were adjusted to recalculate DEA efficiency scores. The efficiency scores and rankings in Stage 1 and Stage 3 DEA are listed in Table 3.5.

Table 3.5 Stage 1 and Stage 3 DEA results (2008)

No Company	Efficiency		Rank	
	Stage1	Stage3	Stage1	Stage3
1 ADAPTEC	0.626	1	19	1
2 ALTERA	1	0.968	1	20
3 BROADCOM	0.948	1	13	1
4 CIRRUS LOGIC	0.575	1	20	1
5 MARVELL TECHNOLOGY GROUP	0.635	0.869	18	23
6 NVIDIA	0.858	1	14	1
7 OMNIVISION TECHNOLOGIES	0.395	0.904	28	22
8 PMC-SIERRA	0.675	0.981	17	19
9 QLOGIC	1	0.73	1	26
10 QUALCOMM	1	1	1	1
11 SANDISK	1	0.795	1	24
12 SEMTECH	1	1	1	1
13 SILICON LABORATORIES	0.718	1	15	1
14 SILICON STORAGE TECHNOLOGY	0.442	0.921	26	21
15 XILINX	0.967	1	11	1
16 MEDIATEK	1	1	1	1
17 NOVATEK MICROELECTRONICS	1	0.386	1	27
18 REALTEK SEMICONDUCTOR	0.472	1	24	1
19 COASIA MICROELECTRONICS	1	0.374	1	28

20 VIA TECHNOLOGIES	0.388	0.785	29	25
21 ETRON TECHNOLOGY	0.298	1	30	1
22 RICHTEK TECHNOLOGY	1	0.2	1	29
23 SITRONIX TECHNOLOGY	0.965	1	12	1
24 SUNPLUS TECHNOLOGY	0.432	1	27	1
25 SILICON INTEGRATED SYSTEMS	0.566	1	21	1
26 FARADAY TECHNOLOGY	0.451	1	25	1
27 ELITE SEMICONDUCTOR MEMOR Y	0.487	1	23	1
28 PIXART IMAGING	1	0.169	1	30
29 ELAN MICROELECTONICS	0.488	1	22	1
30 SONIX TECHNOLOGY	0.705	1	16	1

Spearman's rank correlation was employed to evaluate the influence of environmental factors and luck. As shown in Table 3.6, after adjusting for the influence of environmental variable and statistical noise, mean efficiency score improves and standard deviation declines. The Spearman's rank correlation coefficient between Stage1 and Stage3 is -0.3280 but not significant. The results suggested that many firms with high rankings in Stage 1 DEA do not necessarily perform well in Stage 3 DEA. The low correlation implies that the influence of environmental variables and luck is large. Therefore, it is important to isolate these effects before measuring managerial efficiency.

Table 3.6 Comparison of Stage1 and Stage3 DEA results.(2008)

	Stage1 results	Stage3 results
Mean efficiency score	0.736	0.869
Standard deviation	0.251	0.248
Minimum	0.298	0.169
Maximum	1	1
Number of efficient firms	10	18

*Spearman's rank correlation coefficient between Stage1 and Stage3 is -0.3280 but not significant at 5% level.

To further analyze the relative strengths of IC design houses, this study categorized all firms

according to their efficiency and gross margins using 2008 data. All companies are divided into four groups according to their efficiency scores (X axis) and gross margins (Y axis). Following previous research, 0.8 is used as a cutoff point to specify high and low efficiency (Yang and Lu, 2006; Lu and Lo, 2007). Besides, 40% gross margin is an important threshold for IC design companies to gain competitive edge from the perspective of practitioners in IC design industry (Tsai, 2000).

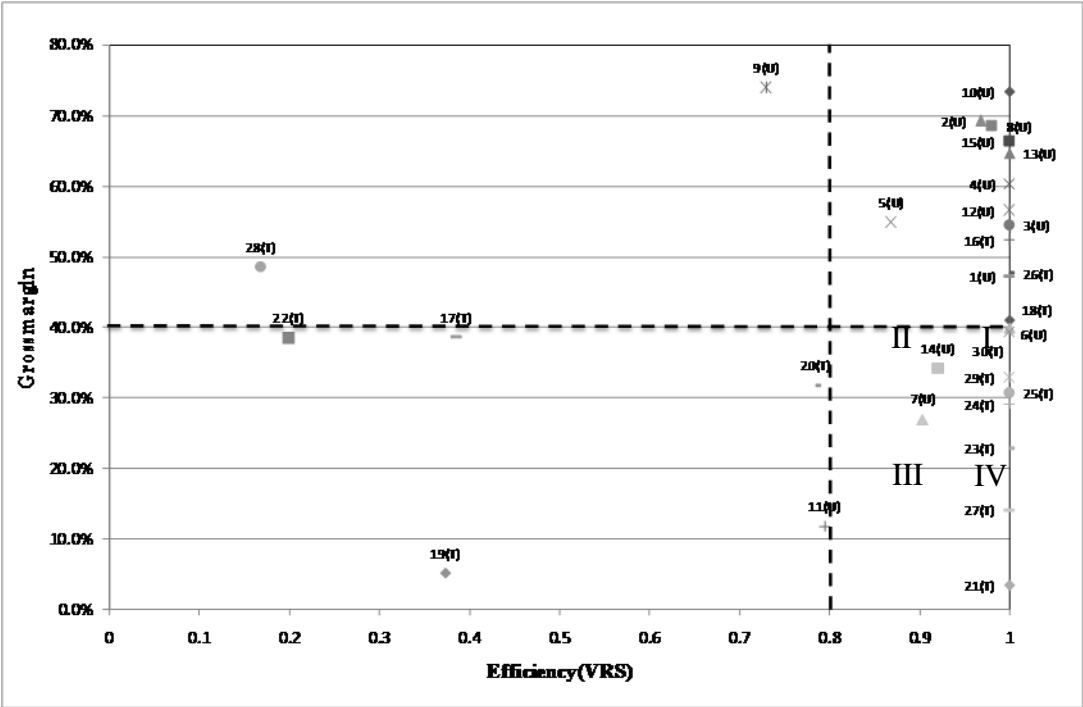


Fig. 3-1 Efficiency and gross margin of IC design houses in 2008

As shown in Fig. 3-1, the graph is divided into quadrant I (high efficiency and high margin), quadrant II (low efficiency but high margin), quadrant III (low efficiency and low margin), and quadrant IV (high efficiency but low margin). These categories are characterized as follows:

(1) *High efficiency and high gross margin:* The best firms located in quadrant I are those with

superior efficiency and high gross margin. These companies produce higher-end products and operate efficiently compared to their counterparts. As Figure 1 indicates, 10 US firms except 3 Taiwanese firms are located in quadrant 1.

(2) *Low efficiency but high gross margin:* There are 1 US firms and 1 Taiwanese firms falling in quadrant II. These companies have selected right product strategies; however, they need to improve their operating efficiency further more.

(3) *Low efficiency and low gross margin:* The worst firms located in quadrant III are those with low efficiency and low gross margin. There are 1 US firms and 5 Taiwanese firms located in quadrant III. To keep competitive, these firms have to upgrade their technology level and improve their managerial capabilities at the same time. It is a warning signal for those firms located in this quadrant that they may be weeded out by their competitors in the future.

(4) *High efficiency but low gross margin:* Quadrant IV includes 3 US firms and 7 Taiwanese ones. Although these firms have operated efficiently, they need to improve their gross margins by developing more advanced products.

The firms in different quadrants are summarized in Table 3.7. The result shows that, in general, US firms outperform Taiwanese firms.

Table 3.7 IC design houses in different quadrants

Quadrant	No	Company	Country	Efficiency	Margin
1	10	QUALCOMM	US	1	73.5%
1	15	XILINX	US	1	66.4%
1	13	SILICON LABORATORIES	US	1	64.7%
1	4	CIRRUS LOGIC	US	1	60.3%
1	12	SEMTECH	US	1	56.6%
1	3	BROADCOM	US	1	54.5%
1	16	MEDIATEK	Taiwan	1	52.4%
1	26	FARADAY TECHNOLOGY	Taiwan	1	47.7%

1	1	ADAPTEC	US	1	47.2%
1	18	REALTEK SEMICONDUCTOR	Taiwan	1	41.0%
1	8	PMC-SIERRA	US	0.981	68.6%
1	2	ALTERA	US	0.968	69.3%
1	5	MARVELL TECHNOLOGY GROUP	US	0.869	54.9%
2	9	QLOGIC	US	0.73	74.0%
2	28	PIXART IMAGING	Taiwan	0.169	48.6%
3	11	SANDISK	US	0.795	11.7%
3	20	VIA TECHNOLOGIES	Taiwan	0.785	31.8%
3	17	NOVATEK MICROELECTRONICS	Taiwan	0.386	29.2%
3	19	COASIA MICROELECTRONICS	Taiwan	0.374	5.2%
3	22	RICHTEK TECHNOLOGY	Taiwan	0.2	38.4%
4	6	NVIDIA	US	1	39.9%
4	30	SONIX TECHNOLOGY	Taiwan	1	39.3%
4	29	ELAN MICROELECTONICS	Taiwan	1	32.9%
4	25	SILICON INTEGRATED SYSTEMS	Taiwan	1	30.7%
4	24	SUNPLUS TECHNOLOGY	Taiwan	1	29.1%
4	23	SITRONIX TECHNOLOGY	Taiwan	1	22.9%
4	27	ELITE SEMICONDUCTOR MEMORY	Taiwan	1	14.1%
4	21	ETRON TECHNOLOGY	Taiwan	1	3.5%
4	14	SILICON STORAGE TECHNOLOGY	US	0.921	34.2%
4	7	OMNIVISION TECHNOLOGIES	US	0.904	27.0%

3.7. Discussion and Conclusion

This study aimed to include dominant players of IC design industry and employ three-stage DEA to analyze their relative capabilities. The three-stage DEA approach has the advantages over the traditional financial ratios due to its multi-dimensional characteristics. In addition, the three-stage DEA can purge the influence of environmental factors to get the “pure” managerial efficiency and thus to measure managerial capability of firms. This research applied three-stage DEA, isolating the influence of environment and luck, to evaluate the managerial capability of IC design houses in US and Taiwan. The results of this study may provide a reference for future research in different context.

This research provides some managerial implications for practitioners in the IC design industry. Practitioners in IC design industry may concern whether the operating environment in US is superior to that in Taiwan. As shown in empirical results, the country dummy variable is not significant for all three input slacks. Although US firms own more advanced technology, the empirical findings suggested the operating environment in Taiwan is not inferior to that in US. Besides, different product categories to which the firms belong will not result in inefficiency. In conclusion, the environmental variables characterizing the differences between US and Taiwan are not the sources of inefficiency. Those firms with low efficiency have nothing to blame but their managerial capability.

Finally, this research also reveals the relative competitive positions of IC design houses in US and Taiwan. In comparison with Taiwanese IC design firms, US firms are more efficient and their gross margins are also higher. Most of the US firms located in high-efficiency/high-margin quadrant are the top players like Qualcomm, Broadcom and Xilinx. There are only 3 Taiwanese companies, MediaTek, Faraday and Realtek, located in the quadrant with high efficiency and gross margin. Qualcomm and Broadcom are the leaders in wireless and wired communication sectors respectively. MediaTek is the largest supplier of mobile phone chips in China. Xilinx, and Faraday are major providers of IC design services in US and Taiwan. The products of these firms enjoy high profit margins and own high growth potential in the future.

On the contrary, many Taiwanese IC design firms are located in low-efficiency/low-margin or high-efficiency/low-margin quadrant. In general, Taiwanese firms mostly product PC-related or consumer-related products which are on lower technology level and in mature stage. That is why the gross margins of Taiwanese firms are lower than those of their US counterparts. Although many Taiwanese IC design houses can use their competitive strengths (speed, quality, flexibility and costs) to compete, one of the competitive strengths, low-cost manufacturing ability,

has begun to erode since the rise of developing economics like China and India. In addition, Silicon Valley is now transferring its advanced design technologies to China. Taiwanese IC design firms should not only rely on low-cost manufacturing but upgrade design capabilities to maintain its competitive advantages. For example, MediaTek, the most successful IC design company in Taiwan, has expanded its product lines from multimedia ICs to mobile phone ICs and captured more than 50% of market share in China for the recent years. Its continuous efforts to upgrade technology and product level make itself a top player in IC design industry.

It is a warning signal for those IC design houses located in the low-efficiency/low-margin quadrant. These companies need to improve operating efficiency and upgrade their technology level in order to improve their gross margins. Otherwise, these firms may not survive the hyper-competition of IC design industry.

This study is the first one to include all dominant players of IC design industry and employ three-stage DEA to analyze their relative capabilities. The three-stage DEA approach has the advantages over the traditional financial ratios due to its multi-dimensional characteristics. In addition, the three-stage DEA can purge the influence of environmental factors to get the “pure” managerial efficiency thus to measure managerial capability of firms. This research applied three-stage DEA, isolating the influence of environment and luck, to evaluate the managerial capability of IC design houses in US and Taiwan. The results of this study may provide a useful reference for future research in different context.

The empirical results provide several useful implications for academics and practitioners. For academics, this study reveals that managerial capability is the major source of inefficiency. As indicated by the estimated value of γ , statistical noise accounts for only 13-18% of influence on efficiency. Besides, the high correlation between Stage 1 DEA and Stage 3 DEA efficiency

scores suggested that environmental influence is small. In other words, managers still have much room to improve even if their firms operate either in a relatively poor environment or with bad luck. Managerial capability is the dominant factor to be competitive in IC design industry. The findings are consistent with the RBV theory which ascribes the performance of firms to their unique competencies.

This research also provides some managerial implications for practitioners in the IC design industry. Practitioners in IC design industry may concern whether the operating environment in US is superior to that in Taiwan. As shown in empirical results, the country dummy variable is not significant for all three input slacks. Although US firms own more advanced technology, the empirical findings suggested the operating environment in Taiwan is not inferior to that in US. Besides, different product categories to which the firms belong will not result in inefficiency. In conclusion, the environmental variables characterizing the differences between US and Taiwan are not the sources of inefficiency. Those firms with low efficiency have nothing to blame but their managerial capability.

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It is a warning signal for those IC design houses located in the low-efficiency/low-margin quadrant. These companies need to improve operating efficiency and upgrade their technology level in order to improve their gross margins. Otherwise, these firms may not survive the hyper-competition of IC design industry.

Chapter 4. Empirical Study on Intellectual Capital Management

4.1. Research background

With the advent of new economy, the role of knowledge in achieving competitive advantages has received much attention in management field. The resource-based view (RBV), which is increasingly popular in strategic management, links superior performance to resources and capabilities owned by firms (Peteraf, 1993; Teece, 1980; Barney, 1991; Wernerfelt, 1984). As suggested by RBV, resources and capabilities that are rare, valuable, inimitable, and non-substitutable will be the sources of sustainable competitive advantages (Barney, 1991). Resources and capabilities will be hard to imitate if they are tacit, complex and specific (Reed and DeFillipi, 1990).

Extended from RBV, the knowledge-based view (KBV) further emphasizes that knowledge is the most productive resource of the organization (Nonaka, 1994; Kogut and Zander, 1992; Grant 1996; Yang and Chen, 2007). While the resources, capabilities and knowledge proposed by RBV or KBV are critical to firms' competitive advantages, they seldom appear on the balance sheets of firms. Many valuable intangible assets such as R&D, patents, copyrights, customer lists and brand equity are often not included in financial reports. Traditional accounting practice does not provide adequate measurement for identifying and measuring these "knowledge-based" intangibles in firms, especially knowledge-based firms (Guthrie, 2001).

Lack of proper intellectual capital measurement method may cause many managerial problems. Firms could be only vaguely aware of their investments in intellectual capital and the associated returns. Consequently, managers may frame wrong strategies and thus overinvest or underinvest on key knowledge assets (Wu et al., 2006). The wrong configuration of resources may hurt the future competitive advantages of firms. Since you cannot manage what you cannot

measure, an adequate way to evaluate the effectiveness of managing intellectual capital is essential for managers.

Much research have emphasized the importance of intellectual capital (Edvinsson and Malone, 1997; Stewart, 1997; Bontis, 2001). However, studies of intellectual capital management from an empirical perspective are still insufficient (Wu et al., 2006). This study employed DEA and PCA methodology to evaluate the efficiency of managing intellectual capital for 62 IC design firms in Taiwan. Since IC design firms rely little on physical capital investment, intellectual capital is the key factor to succeed in IC design industry. Thus, the IC design industry is an ideal sample for research on intellectual capital. Using the efficiency scores generated from DEA, PCA technique was employed to explore the relationship between different DEA models.

This research attempts to propose a tool to reveal the relative competitive positions of managing intellectual capital from an empirical perspective. The findings could be helpful for practitioners in IC design industry to understand their competitive strengths on intellectual capital and to frame their future strategies by benchmarking their counterparts.

4.2. Measurement of intellectual capital management

To meet the need for measuring the value of intellectual capital in firms, much research has devoted to propose new measurement methods in recent years. Sveiby (1997) classified four main measuring approaches: (1) direct intellectual capital methods, (2) market capitalization methods, (3) return on assets methods and (4) scorecard methods. Edvinsson and Malone (1997) and Roos et al. (1997) have suggested that intellectual capital is the hidden value which can be represented by the difference between the market value and book value of a firm. Market value added (MVA) has been popular in many studies for its simplicity and ease of use. However, opponents of this method argue that MVA is sensitive to the rises and falls of stock market and

cannot give a fixed value of intellectual capital. Calculated intangible value (CIV), overcoming the drawbacks of MVA, examines earnings performance and identifies the assets producing those earnings (Stewart, 1997). By comparison, MVA reflects market's expectation about firms' future cash flow, while CIV reflects firms' ability to attain above-average return on assets (ROA). In this study, these two popular measures, MVA and CIV, were both employed to estimate the value of intellectual capital.

4.3. Data Envelopment Analysis

Data envelopment analysis (DEA) is a linear programming technique, introduced by Charnes et al. (1978) and extended by Banker et al. (1984), provides a non-parametric method for estimating production frontier and evaluating the relative efficiency of decision making units (DMUs). Land et al. (1993) further extended DEA to the case of stochastic inputs and outputs through the use of chance-constrained programming. Banker (1993) also provided a formal statistical basis for the efficiency evaluation techniques of DEA and suggested possible statistical tests of hypotheses based on asymptotic distributions. Knip and Simar (1996) proposed a general framework for estimating production frontier models with panel data. Simar and Wilson (2000) provided the asymptotic sampling distribution of the FDH estimator in a multivariate setting and of the DEA estimator in the bivariate case. Thus statistical inference based on DEA/FDH-type estimators is made possible. These valuable studies pave the way for DEA to extend to statistical inferences.

When some output quantities are negative, it will be necessary to add a constant to the measured quantities to run DEA models. However, it is important to recognize that some of the DEA measures of efficiency will be affected by certain kinds of data transformation. If the optimal solution of the DEA model remains unchanged after adding a constant, the model is

called translation invariant. The input-oriented BCC model is translation invariant with respect to outputs (Ray, 2004). To keep the translation invariant property of DEA modes, this research adopt the deterministic approach rather than stochastic approach. If the output quantities are positive, future studies may apply stochastic approach to eliminate the effect of random errors.

4.4. Combination of DEA and PCA

DEA approach has the advantages over single-measure approach due to its multi-dimensional (multi-inputs and multi-output) characteristics. However, efficiency scores are sensitive to the inputs and outputs a DEA model employed. A better way to analyze data is to compare different combinations of inputs and outputs then see their differences. Serrona-Cinca et al. (2005) proposed principal components analysis (PCA) is helpful to reveal the similarities and differences of various DEA models.

The combination of DEA and PCA techniques first uses DEA to estimate efficiencies all proposed models then visualize the results by means of PCA. PCA can visualize what is similar and what is different among the various models. Although MVA and CIV are often used as performance measures in intellectual capital research, their similarities/differences are seldom compared. The combination of DEA and PCA techniques is a useful tool to explore the relationship of these two performance measures.

4.5. Methodology

4.5.1. Data Envelopment Analysis (DEA)

When applying DEA models, two different assumptions, constant returns to scale (CRS) and variable returns to scale (VRS), may be adopted. The CRS assumption (also called CCR model)

is appropriate when all firms are operating at an optimal scale. Banker, Charnes and Cooper (1984) suggested adjusting the CRS DEA model to account for variable returns to scale (VRS) (also called BBC model) situations if not all firms are operating at the optimal scale. This study adopted an input-oriented approach and the assumption of variable return to scale (VRS) to formulate the linear programming problem :

$$\begin{aligned} \text{Subject to } \quad & \theta x^0 \geq X\lambda \\ & Y\lambda \geq y^0 \\ & \lambda \geq 0 \\ & e^T \lambda = 1 \end{aligned}$$

where $X \geq 0$ denotes $N \times I$ vector of inputs, $Y \geq 0$ denotes $M \times I$ vector of outputs, $X = [x_1, \dots, x_I]$ is an $N \times I$ matrix of input vectors, $Y = [y_1, \dots, y_I]$ is an $M \times I$ matrix of output vectors, $\lambda = [\lambda_1, \dots, \lambda_I]$ is an $I \times 1$ vector of intensity variables, $e = [1, \dots, I]$, and there are I producers in the comparison set. The optimal values of θ , solved by the above linear program equation, will fall between 0 and 1.

The models using different performance indices will be run to calculate their efficiency scores for principal component analysis.

4.5.2. Principal Component Analysis (PCA) and Biplot

The efficiency scores generated from DEA analysis will be analyzed by PCA. PCA is a data reduction technique owning the benefits of removing redundant information, highlighting hidden feature of data, and visualizing the main relationship between observations (Serrano-Cina et al., 2005). The results of PCA will be depicted as biplots to visualize the similarities/differences

between models and the relative strengths of firms.

4.6. Data

Most of the IC design companies in Taiwan are small to medium size. The major players often go public to raise their capital. The data employed in this study were collected from Taiwan Economic Journal (TEJ) electronic database. All the public listed companies of IC design sector in Taiwan were included. The aggregated revenues of the selected 62 companies (see Appendix 1) accounted for about 90% of total Taiwan IC design industry revenues in 2009, therefore the selected samples may well represent the whole IC design industry in Taiwan.

The input variable, market value added in 2008 (MVA_2008), was included to represent the monetary value of firms' accumulated intellectual capital stocks (Wu et al., 2006) by 2009. Following previous research in high-tech context, R&D expense (RD) (Verma and Sinha, 2002) and number of employees (EMP) (Wu et al., 2006; Shao and Lin, 2002) were also employed as inputs variables due to their high correlation with intellectual capital. As for output variables, this study adopted two popular methods, calculated intangible value (CIV_2009) (Stewart, 1997) and market value added (MVA_2009) (Deeds et al., 1998) in 2009, to estimate the monetary value of intellectual capital generated by firms. Some firms' CIVs in 2009 are negative and adjusted to positive values. Since the input-oriented BCC model is translation invariant with respect to outputs (Ray, 2004), the resulting efficiency will not be changed.

The CIV method reflects a firm's ability to outperform an average competitor with similar tangible assets. On the other hand, MVA method owns the benefits to reflect all information available to investors (Deeds et al., 1998) and to considers the amount of capital invested in a firm at the same time (Stewart, 1991). At last, net sale was employed as a benchmark in comparison with CIV and MVA. All the inputs and outputs variables are listed in Table 4.1

Table 4.1 Input and output variables

Inputs/outputs	Measure	Mean	Standard deviation
Input			
a	MVA in 2008 (USD ^a in thousands)	156224.5	93485.0
b	Number of employees	303.3	397.4
c	R&D expense (USD in thousands)	22111.7	75322.3
Output			
1	MVA in 2009 (USD in thousands)	116267.0	211459.5
2	CIV in 2009 (USD in thousands)	45519.0	150232.3
2	Sales in 2009 (USD in thousands)	167111.4	472532.5

^a original data were in New Taiwan Dollar (NTD) and transformed into United States Dollar (USD) by adjusting exchange rates.

4.7. Results

4.7.1. DEA results

The efficiencies of all 62 IC design firms were calculated under three difference DEA models. Listed in Table 4.2 are all the 3 DEA models and the efficiency scores under each model. All scores are presented in percentage values.

As shown in Table 4.2, the efficiency scores of firms are various under different performance indices. To show the whole picture of the data in Table 4.2, PCA technique was employed to reveal the relationship between different models.

Table 4.2 DEA efficiencies of IC design firms under different performance index

ID	CIV	MVA	Sales	ID	CIV	MVA	Sales
1	100	100	100	32	90	98	100
2	44	56	73	33	86	94	84
3	19	32	23	34	100	98	98
4	89	60	100	35	83	100	78

5	68	97	67	36	78	77	78
6	100	100	100	37	84	95	82
7	46	100	40	38	100	100	100
8	88	70	67	39	100	73	83
9	77	75	73	40	89	94	89
10	68	46	46	41	66	64	52
11	100	100	100	42	97	96	96
12	52	88	38	43	94	94	94
13	68	100	69	44	83	70	65
14	86	96	100	45	95	79	69
15	86	95	83	46	77	79	68
16	82	87	81	47	100	100	100
17	91	91	89	48	100	100	100
18	83	84	82	49	98	98	98
19	62	84	59	50	71	64	53
20	67	74	64	51	100	100	100
21	83	75	75	52	84	88	75
22	93	99	93	53	74	81	69
23	86	89	83	54	49	82	43
24	92	97	95	55	91	91	89
25	87	87	82	56	76	56	63
26	86	73	80	57	89	87	86
27	83	85	79	58	82	74	72
28	38	52	41	59	76	65	64
29	83	73	74	60	74	66	66
30	69	55	60	61	100	100	100
31	76	83	76	62	72	62	100

4.7.2. PCA results and biplots

The efficiency scores generated from DEA analysis was used to conduct PCA analysis to make clear the relationships among different DEA models. The first principal component accounts for 80.4% of the total variance. The second principal component accounts for additional 15.12% of the variance. The first two principal components account for 95.5% of the total

variance. The eigenvalues and proportions of variance for three principal components are listed in Table 4.3.

Table 4.3 Eigenvalues and proportion of variance

	Eigenvalue	Difference	Proportion	Cumulative
PC1	2.41195125	1.95831500	0.8040	0.8040
PC2	0.45363625	0.31922375	0.1512	0.9552
PC3	0.13441250	0.0448	1.0000	

All three models load with positive sign on the first component. MVA model loads with positive sign on the second component, while the CIV and Sales models load with negative sign. As shown in Table 4.4, CIV model are similar to Sales model, while MVA model is distinct from them. According to their relationships, Prin1 is named “overall performance”, while Prin2 is named “future expectation performance”.

Table 4.4 Matrix of component loadings

Model	Prin1	Prin2	Prin3
CIV model	0.598285	-.397160	0.695930
MVA model	0.528341	0.848502	0.030021
Sales model	0.602421	-.349727	-.717482

The result of PCA analysis was depicted as the biplot in Fig. 4-1. There are 3 directional vectors associated with the 3 DEA models. If the angle between any two vectors is small, the efficiency scores generated from these two models are highly correlated. This also implies the two models are interchangeable. On the other hand, if the two vectors are orthogonal to each other, the efficiency scores calculated from the two models will be independent. Fig. 4-1 shows three directional vectors to illustrate the relationships between different performance models.

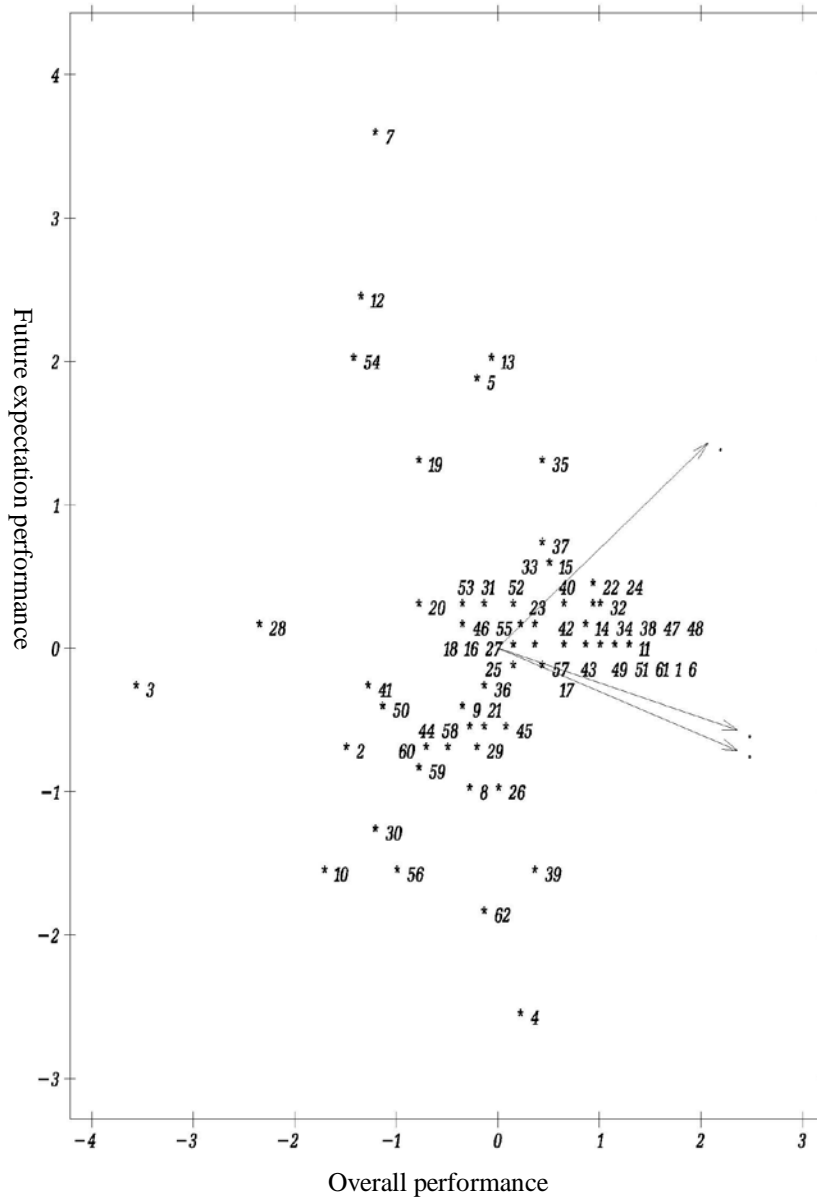


Fig. 4-1 Oriented vectors using different performance indices

The Spearman’s rank correlation coefficient of CIV model and MVA model is 0.61, while the correlation of Sales model and MVA model is 0.63. The correlation indicates that MVA efficiency is correlated with Sales and CIV efficiency but distinct from them. Besides, the correlation of CIV model and Sales model is 0.85. As shown in Fig. 4.1, the high correlation between Sales and CIV models implies both these two performance indices reflect the present

operating performance of firms. MVA model, on the other hand, reflect the expectation about firms' future cash flow.

The strengths and weaknesses of individual firms can be revealed by inspecting their position relative to specific directional vectors. Some companies with 100% efficient may only excel in one dimension. To further clarify the relative strength of IC design firms, all firms are classified into four groups in Table 4.5 according to their efficiency scores in MVA and CIV dimensions (80% efficient used as a cutoff to separate high/low groups). As mentioned in the preceding paragraphs, MVA reflects market's expectation about firms' future cash flow, while CIV reflects firms' ability to attain above-average ROA. The firms located in high MVA/high CIV quadrant are those with excellent performance in both dimensions. The firms located in high MVA/low CIV quadrant have good potential in the future yet need to keep improving their ROA performance. On the other hand, the firms located in low MVA/high CIV quadrant are quite successful in present operation. However, they may need to be more innovative to attract market's attention. Finally, the companies in low MVA/low CIV quadrant should be cautious since they are inferior to their counterparts in both performance dimensions.

Table 4.5 Relative competitive position of IC design firms

CIV efficiency	MVA efficiency	Company ID
High	High	1, 6, 11, 14, 15, 16, 17, 18, 22, 23, 24, 25, 27, 32, 33, 34, 35, 37, 38, 40, 42, 43, 47, 48, 49, 51, 52, 55, 57, 61
High	Low	4, 8, 21, 26, 29, 39, 44, 45, 58
Low	High	5, 7, 12, 13, 19, 31, 53, 54
Low	Low	2, 3, 9, 10, 20, 28, 30, 36, 41, 46, 50, 56, 59, 60, 62

4.8. Conclusion

Management of intangible assets has been an increasingly critical issue for firms to keep their competitiveness in new economy. An adequate measurement of managing efficiency is essential for managers to understand their relative competitive position and frame their future competitive strategy. Much previous research (Edvinsson and Malon, 1997; Stewart, 1997; Bontis, 2001) discussed the content of intellectual capital from a more conceptual aspect. Empirical research on intellectual capital management has been increasing yet more empirical studies are still in need (Wu et al., 2006). This research may contribute to the literature of intellectual capital management empirically, especially in the high-technology context.

MVA and CIV are two popular performance measures in research of intellectual capital management. However, the similarities/differences of the two measures are seldom explored, especially under DEA context. This study showed MVA and CIV efficiencies are related but distinct concept. MVA reflects firms' future prospects, while CIV reflects firms' present performance. Future studies should notice the differences when applying these two measurements.

This research also reveals the competitive landscape of IC design firms along MVA and CIV

performance dimensions. There are 30 companies achieving high efficiency on both dimensions. These firms received high expectation from market and achieved high above-average ROA at the same time. There are 8 companies with high MVA but low CIV efficiency. These firms have future potential but must improve their returns on assets. On the contrary, the 9 firms with high CIV but low MVA efficiency may need to adjust their product lines to grasp the attention of market. Finally, the remaining 15 firms with low MVA and CIV efficiency need to improve their present operation and adjust product lines at the same time. The results provide a reference for managers of IC design firms to understand their relative strength and weakness in intellectual capital management. Thus managers can frame their future strategy correctly and efficiently.

IC design houses in Taiwan have been successful in competing on their competitive strengths - speed, quality, flexibility and costs. However, one of the competitive strengths, low-cost manufacturing ability, has begun to erode since the rise of developing economics like China and India. In addition, Silicon Valley is now transferring its advanced design technologies to China. Taiwanese IC design firms should not only rely on low-cost manufacturing but upgrade their design capabilities to maintain its competitive advantages. It is a warning signal for those IC design companies located in the low MVA/low CIV efficiency quadrant. These companies need not only to improve the operating efficiency now but also to upgrade their technology level in order to promote their future value. Otherwise, these firms may not survive the hyper-competition of IC design industry.

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Appendix 1 IC design companies in Taiwan

ID	Company	ID	Company
1	Silicon Integrated Systems Corp.	32	Zentel Electronics Corp.
2	Realtek Semiconductor Corp.	33	eGalax-eMPIA Technology Inc.
3	VIA Technologies, Inc.	34	Materials Analysis Technology Inc.
4	Sunplus Technology Co., Ltd.	35	Leadtrend Technology Corp.
5	Weltrend Semiconductor, Inc.	36	Trendchip Technologies Corp.
6	Mediatek Incorporation	37	Syntek Semiconductor Co., Ltd.
7	Elan Microelectronics Corp.	38	Myson Century, Inc.
8	Springsoft Inc.	39	Etron Technology, Inc.
9	Elite Semiconductor Memory Technology	40	TM Technology Inc.
10	ITE Tech. Inc.	41	Sonix Technology Co., Ltd.
11	Novatek Microelectronics Corp.	42	Tontek Design Technology Ltd.
12	Faraday Technology Corp.	43	Avid Electronics Corp.
13	Ali Corp.	44	Genesys Logic, Inc.
14	Prescope Technologies Co., Ltd.	45	Princeton Technology Corp.
15	Davicom Semiconductor, Inc.	46	Anpec Electronics Corp.
16	Acard Technology Corp.	47	Jinglay, Inc.
17	Ame Inc.	48	Scandic International Corp.
18	Service & Quality Technology Co., Ltd.	49	Averlogic Technologies Corp.
19	PixArt Imaging Inc.	50	Holtek Semiconductor Inc.
20	RDC Semiconductor Co., Ltd.	51	V-TAC Technology Co., Ltd.
21	Solid State System Co., Ltd.	52	Prolific Technology Inc.
22	Higher Way Electronic Co., Ltd.	53	C-Media Electronics Inc.
23	Silicon Touch Technology Inc.	54	Richtek Technology Corp.
24	Integrated Service Technology Inc.	55	Analog Integrations Corp.
25	Feeling Technology Corp.	56	Sitronix Technology Corp.
26	Niko Semiconductor Co., Ltd.	57	Alpha Microelectronics Corp.
27	Advanced Analog Technology, Inc.	58	IC Plus Corp.
28	Global Unichip Corp.	59	Alcor Micro Corp.
29	Macroblock, Inc.	60	Global Mixed-Mode Technology Inc.
30	Ralink Technology Corp.	61	Chip Hope Co., Ltd.
31	Orise Technology Co., Ltd.	62	Phison Electronics Corp.